

# TNG04P60SG

## P-Channel Enhancement Mode Power MOSFET

## **Product Summary**

- V<sub>DS</sub>= -60V,I<sub>D</sub>= -4A
- $R_{DS(on)} < 95m\Omega @V_{GS} = -10V$
- $R_{DS(on)}$ < 130m $\Omega$  @ $V_{GS}$ = -4.5V

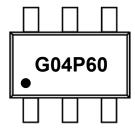
#### **Features**

- Advanced Split Gate Trench Technology
- 100% Avalanche Tested
- RoHS and Reach Compliant
- Halogen and Antimony Free
- Moisture Sensitivity Level 3

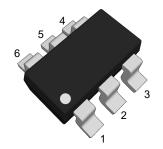
## **Application**

- Load Switch
- PWM Applications
- Power Management

## **Marking Code**



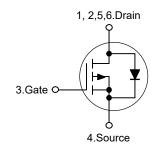
## **SOT-23-6**



(Top View)

Pin Description	
1,2,5,6	Drain
3	Gate
4	Source

## **Schematic Diagram**



## **Absolute Maximum Ratings**

Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbol	Value	Unit
Drain-Source Voltage	-V <sub>DS</sub>	60	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous	-I <sub>D</sub>	4	А
Drain Current-Pulsed Note1	-I <sub>DM</sub>	16	А
Maximum Power Dissipation	P <sub>D</sub>	1.2	W
Junction Temperature	TJ	150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C

## **Thermal Characteristics**

Thermal Resistance,Junction-to-Ambient Note2	ReJA	104	°C/W
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#### **Electrical Characteristics**

(T<sub>J</sub>=25°C unless otherwise specified)

Parameter	Combal	Symbol Test Conditions	Value			
	Symbol		Min.	Тур.	Max.	Unit
Static Parameters						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V, I_{D} = -250\mu A$	-60			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -60V, V <sub>GS</sub> = 0V			-1	μΑ
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS}$ = $\pm 20V$			±100	nA
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-2.0	-2.8	-4.0	V
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -6A		83	100	mΩ
Forward Transconductance	g <sub>FS</sub>	$V_{DS} = -5V, I_{D} = -6A$		7		S
Dynamic Parameters	l					
Input Capacitance	C <sub>iss</sub>			1000		pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0V$ , $V_{DS} = -30V$ , f = 1.0MHz		40		
Reverse Transfer Capacitance	C <sub>rss</sub>			37		
Total Gate Charge	$Q_g$	V 20V		16		
Gate-Source Charge	$Q_{gs}$	$V_{DD} = -30V,$ $I_{D} = -6A,$ $V_{GS} = -10V$		3.4		nC
Gate-Drain Charge	$Q_{gd}$			3.5		
Turn-on Delay Time	t <sub>d(on)</sub>	$V_{DD}$ = -30V, $I_{D}$ = -6A, $R_{G}$ = $6\Omega$		12		
Turn-on Rise Time	t <sub>r</sub>			10		
Turn-off Delay Time	$t_{d(off)}$			19		ns
Turn-off Fall Time	t <sub>f</sub>			6		
Drain-Source Body Diode Characte	ristics					
Continuous Body Diode Current	Is	T <sub>C</sub> = 25°C			-4	Α
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25^{\circ}C$ , $I_{SD} = -6A$ , $V_{GS} = 0V$			-1.2	V
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = -6A, V <sub>GS</sub> = 0V di/dt=-100A/us		40		nC
Reverse Recovery Time	Trr			25		ns

#### **Notes**

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. EAS condition : Tj=25°C ,VDD=-50V,VGS=-10V,L=0.5mH,Rg=25 $\Omega$ The table shows the minimum avalanche energy, which is 42mJ when the device is tested until failure
- 3. Identical low side and high side switch with identical  $R_{\mbox{\scriptsize G}}$

## **Test Circuit**

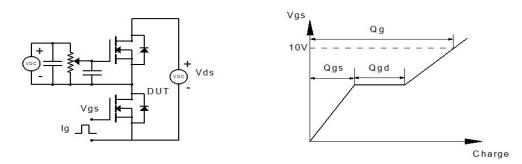


Figure 1: Gate Charge Test Circuit & Waveform

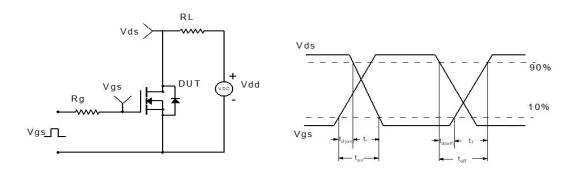


Figure 2: Resistive Switching Test Circuit & Waveform

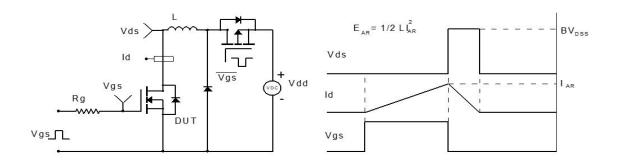


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

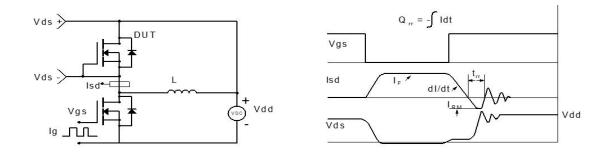


Figure 4: Diode Recovery Test Circuit & Waveform

## **Typical Operating Characteristics**

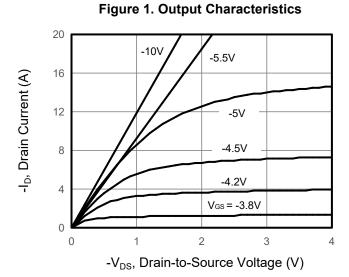


Figure 2. Transfer Characteristics

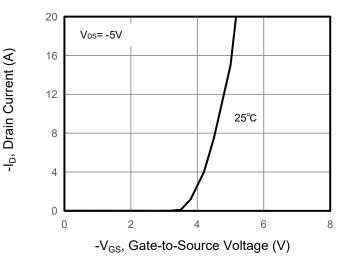


Figure 3.Drain Source On Resistance

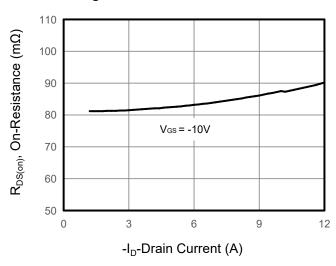


Figure 4. Gate Charge

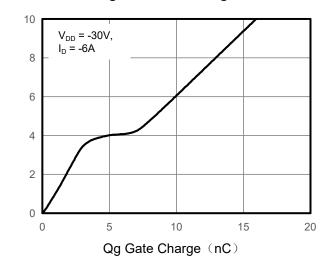


Figure 5. Capacitance

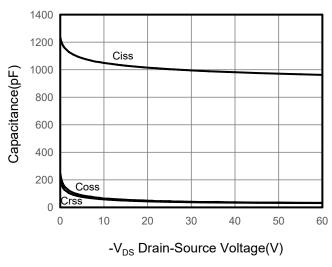
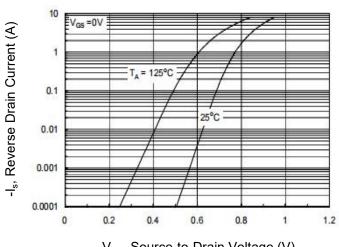


Figure 6. Source-Drain Diode Forward



- $V_{SD}$ , Source-to-Drain Voltage (V)

-Vgs Gate-Source Voltage (V)

## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Figure 7. Drain-Source On-Resistance

1.8

V<sub>GS</sub> = -10V,
I<sub>D</sub> = -6A

1.4

1.2

0.8

0 25 50 75 100 125 150 175

T<sub>J</sub>, Junction Temperature (°C)

Figure 9. Maximum Continuous Drain Current vs Case Temperature

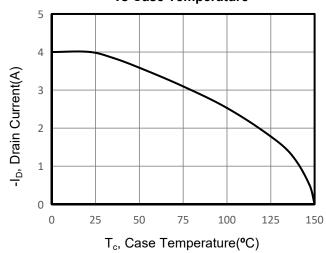
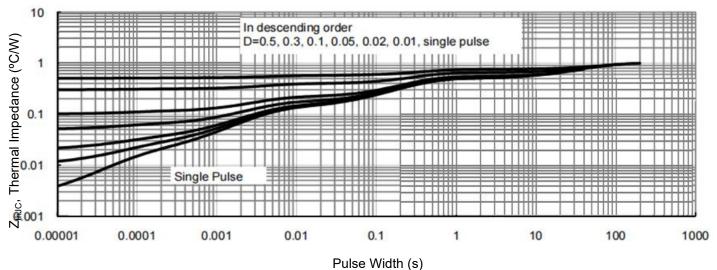


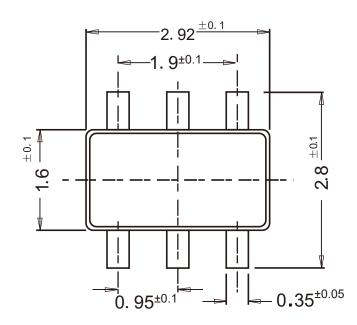
Figure 10. Normalized Maximum Transient Thermal Impedance

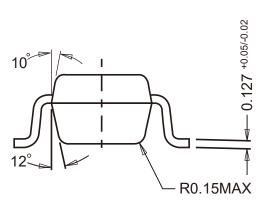


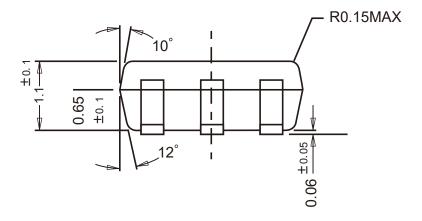
## **Package Outline**

SOT-23-6

Dimensions in mm





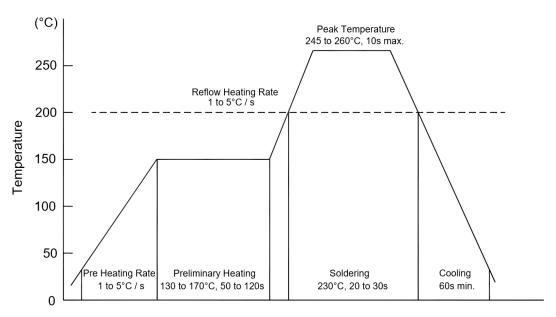


## **Ordering Information**

Device	Package	Shipping
TNG04P60SG	SOT-23-6	3,000PCS/Reel&7inches

## **Conditions of Soldering and Storage**

#### Recommended condition of reflow soldering



Recommended peak temperature is over 245°C. If peak temperature is below 245°C, you may adjust the following parameters:

- Time length of peak temperature (longer)
- Time length of soldering (longer)
- Thickness of solder paste (thicker)

## ◆ Conditions of hand soldering

• Temperature: 300°C

Time: 3s max.Times: one time

#### **♦** Storage conditions

Temperature

5 to 40°C

Humidity

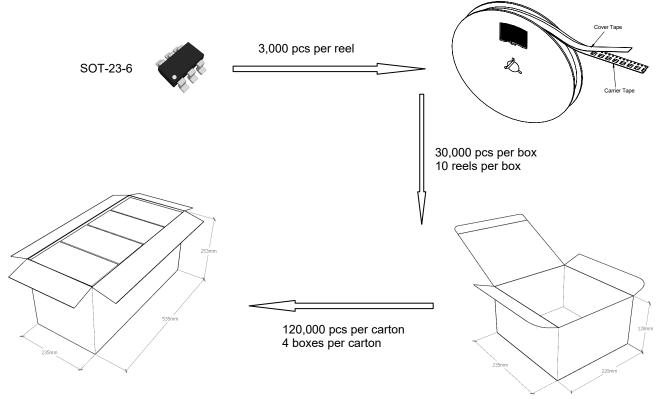
30 to 80% RH

Recommended period

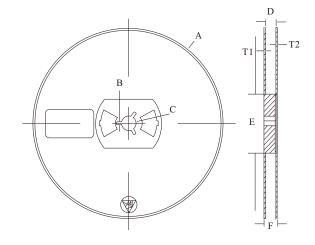
One year after manufacturing

## **Package Specifications**

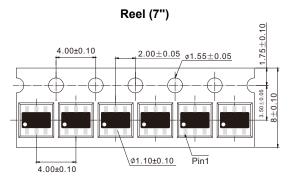
The method of packaging



## ♦ Embossed tape and reel data



Symbol	Value (unit: mm)
Α	Ø 177.8±1
В	2.7±0.2
С	Ø 13.5±0.2
E	Ø 54.5±0.2
F	12.3±0.3
D	9.6+2/-0.3
T1	1.0±0.2
T2	1.2±0.2



Tape (8mm)

#### **Contact Information**

TANI website: http://www.tanisemi.com Email:tani@tanisemi.com

For additional information, please contact your local Sales Representative.



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#### **Product Specification Statement**

The product specification aims to provide users with a reference regarding various product parameters, performance, and usage. It presents certain aspects of the product's performance in graphical form and is intended solely for users to select product and make product comparisons, enabling users to better understand and evaluate the characteristics and advantages of the product. It does not constitute any commitment, warranty, or guarantee.

The product parameters described in the product specification are numerical values, characteristics, and functions obtained through actual testing or theoretical calculations of the product in an independent or ideal state. Due to the complexity of product applications and variations in test conditions and equipment, there may be slight fluctuations in parameter test values. TANI shall not guarantee that the actual performance of the product when installed in the customer's system or equipment will be entirely consistent with the product specification, especially concerning dynamic parameters. It is recommended that users consult with professionals for product selection and system design. Users should also thoroughly validate and assess whether the actual parameters and performance when installed in their respective systems or equipment meet their requirements or expectations. Additionally, users should exercise caution in verifying product compatibility issues, and TANI assumes no responsibility for the application of the product. TANI strives to provide accurate and up -to- date information to the best of our ability. However, due to technical, human, or other reasons, TANI cannot guarantee that the information provided in the product specification is entirely accurate and error-free. TANI shall not be held responsible for any losses or damages resulting from the use or reliance on any information in these product specifications.

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